

IN THE CLAIMS:

Please cancel claims 20-28 without prejudice and amend the claims as follows:

1. (Currently Amended) A system for measuring circuits on an integrated circuit substrate, comprising:

a measurement circuit formed on the integrated circuit substrate which measures at least one characteristic of an integrated circuit,

the measurement circuit comprising a power transfer device including a power transfer component, which receives energy from a source where the source does not make physical contact with the integrated circuit substrate to transfer power to the measurement circuit, the measurement circuit including components that mirror behavior of the integrated circuit so that process parameters measured for the components to provide information about processing.

2. (Original) The system as recited in claim 1, wherein the integrated circuit substrate includes a chip formed on a semiconductor wafer.

3. (Original) The system as recited in claim 2, wherein the measurement circuit is formed in a kerf area of the chip.

4. (Original) The system as recited in claim 1, wherein the power transfer device includes an inductor coil and the source transfers energy via inductive coupling.

5. (Original) The system as recited in claim 1, wherein the power transfer device includes a photo sensor and the source transfers energy via light.

6. (Original) The system as recited in claim 5, wherein the photo sensor includes a photodiode and the source includes a laser.

7. (Original) The system as recited in claim 1, wherein the power transfer device includes a capacitor and the source transfers energy via capacitive coupling.

8. (Original) The system as recited in claim 1, wherein the measurement circuit includes a control circuit, which conveys measurement information.

9. (Original) The system as recited in claim 1, wherein the at least one characteristic includes at least one of a layer thickness and a circuit parameter or response.

10. (Currently Amended) A system for measuring circuits on an integrated circuit substrate, comprising:

a semiconductor wafer including a plurality of chips;

a measurement circuit formed on at least one of the chips, the measurement circuit measures at least one characteristic of an integrated circuit,

the measurement circuit including a power transfer component which receives energy from a source where the source does not make physical contact with the semiconductor wafer to transfer power to the measurement circuit; and

a test device including the source, which delivers energy to the power transfer component of the measurement circuit when in alignment with the power transfer component.

11. (Original) The system as recited in claim 10, wherein the measurement circuit is formed in a kerf area of the chip.

12. (Original) The system as recited in claim 10, wherein the power transfer component includes an inductor coil and the source transfers energy via inductive coupling.

13. (Original) The system as recited in claim 10, wherein the power transfer component includes a photo sensor and the source transfers energy via light.

14. (Original) The system as recited in claim 13, wherein the photo sensor includes a photodiode and the source includes a laser.

15. (Original) The system as recited in claim 10, wherein the power transfer component includes a capacitor and the source transfers energy via capacitive coupling.

16. (Original) The system as recited in claim 10, wherein the measurement circuit includes a control circuit, which conveys measurement information.

17. (Original) The system as recited in claim 10, wherein the test device includes a thin film dielectric membrane having the source mounted thereon.

18. (Original) The system as recited in claim 10, wherein the test device includes a probe

ring.

19. (Original) The system as recited in claim 10, wherein the at least one characteristic includes at least one of a layer thickness and a circuit parameter or response.

20-28. (Cancelled)